

TN6707A

NPN General Purpose Amplifier

- These devices is designed for general purpose medium power amplifiers and switches requiring collector currents to 1.0A
- Sourced from process 39.



Absolute Maximum Ratings* T_A=25°C unless otherwise noted

Symbol	Parameter	FPN660	Units
V_{CEO}	Collector-Emitter Voltage	80	V
V _{CBO}	Collector-Base Voltage	100	V
V_{EBO}	Emitter-Base Voltage	5.0	V
I _C	Collector Current - Continuous	1.2	А
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150°C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics T_A=25°C unless otherwise noted

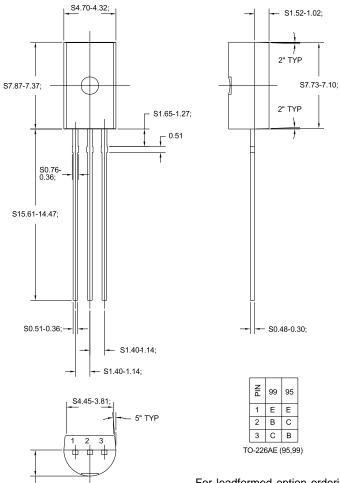
Symbol	Parameter	Test Conditions	Min.	Max.	Units
Off Charac	Off Characteristics				
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage *	$I_C = 10 \text{mA}, I_B = 0$	80		V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$I_E = 100 \mu A, I_E = 0$	100		V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_E = 1.0 \text{mA}, I_C = 0$	5.0		V
I _{CBO}	Collector-Base Cutoff Current	$V_{CB} = 80V, I_{E} = 0$		0.1	μΑ
I _{EBO}	Emitter-Base Cutoff Current	$V_{EB} = 5.0V, I_{C} = 0$		0.1	μΑ
On Characteristics *					
h _{FE}	DC Current Gain	$V_{CE} = 2.0V, I_{C} = 50mA$ $V_{CE} = 2.0V, I_{C} = 250mA$ $V_{CE} = 2.0V, I_{C} = 500mA$	40 40 25	250	
V _{CE} (sat)	Collector-Emitter Saturation Voltage	I _C = 500mA, I _B = 50mA I _C = 1.0A, I _B = 100mA		0.5 1.0	V V
V _{BE} (on)	Base-Emitter On Voltage	$V_{CE} = 2.0V, I_{C} = 1.0A$		1.5	V
Small Sign	nal Characteristics			•	•
h _{fe}	Output Capacitance	$V_{CE} = 5.0V, I_{C} = 200mA, f = 20MHz$	2.5	20	MHz
f _T	Current Gain Bandwidth Product	$V_{CE} = 5.0V$, $I_{C} = 50$ mA, $f = 20$ MHz	50		MHz
* Pulse Test: Pu	lse Width ≤ 300μs, Duty Cycle ≤ 2.0%	•		•	

Thermal Characteristics $T_A=25$ °C unless otherwise noted

Symbol	Parameter	Max.	Units
P _D	Total Device Dissipation	1.0	W
	Derate above 25°C	8.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125	°C/W

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For leadformed option ordering, refer to Tape & Reel data information.

Dimensions in Millimeters

S2.41-2.13; -

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